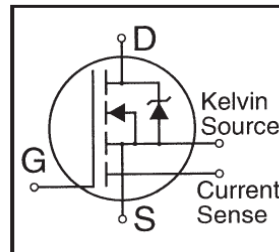


# IRCZ34PbF

## HEXFET® Power MOSFET

- Dynamic dv/dt Rating
- Current Sense
- 175°C Operating Temperature
- Fast Switching
- Ease of Paralleling
- Simple Drive Requirements
- Lead-Free

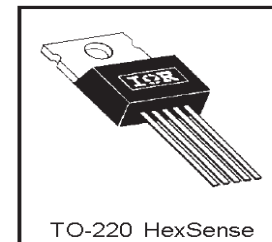


$V_{DSS} = 60V$
$R_{DS(on)} = 0.050\Omega$
$I_D = 30A$

### Description

Third Generation HEXFETs from International Rectifier provide the designer with the best combination of fast switching, ruggedized device, low on-resistance and cost-effectiveness.

The HEXSense device provides an accurate fraction of the drain current through the additional two leads to be used for control or protection of the device. These devices exhibit similar electrical and thermal characteristics as their IRF-series equivalent part numbers. The provision of a kelvin source connection effectively eliminates problems of common source inductance when the HEXSense is used as a fast, high-current switch in non current-sensing applications.



### Absolute Maximum Ratings

Parameter		Max.	Units
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	30	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V$	21	
$I_{DM}$	Pulsed Drain Current ①	120	
$P_D @ T_C = 25^\circ C$	Power Dissipation	88	W
	Linear Derating Factor	0.59	W/C
$V_{GS}$	Gate-to-Source Voltage	$\pm 20$	V
$E_{AS}$	Single Pulse Avalanche Energy ②	15	mJ
dv/dt	Peak Diode Recovery dv/dt ③	4.5	A
$T_J$	Operating Junction and	-55 to + 175	°C
$T_{STG}$	Storage Temperature Range		
	Soldering Temperature, for 10 seconds	300 (1.6mm from case)	
	Mounting Torque, 6-32 or screw	10 lbf•in (1.1 N•m)	

### Thermal Resistance

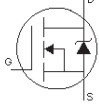
Parameter	Parameter	Min.	Max.	Units	
$R_{\theta JC}$	Junction-to-Case	—	—	1.7	°C/W
$R_{\theta CS}$	Case-to-Sink, Flat, Greased Surface	—	0.50	—	
$R_{\theta JA}$	Junction-to-Ambient	—	—	62	

\*\* When mounted on FR-4 board using minimum recommended footprint. For recommended footprint and soldering techniques refer to application note #AN-994.

## Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise specified)

Parameter	Min.	Typ.	Max.	Units	Conditions
V <sub>(BR)DSS</sub>	60	—	—	V	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA
ΔV <sub>(BR)DSS/ΔT<sub>J</sub></sub>	—	0.065	—	V/°C	Reference to 25°C, I <sub>D</sub> = 1mA
R <sub>DS(ON)</sub>	—	—	0.050	Ω	V <sub>GS</sub> = 10V, I <sub>D</sub> = 18A④
V <sub>GS(th)</sub>	2.0	—	4.0	V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA
g <sub>fs</sub>	9.4	—	—	S	V <sub>DS</sub> = 25V, I <sub>D</sub> = 18A
I <sub>DSS</sub>	—	—	25	—	V <sub>DS</sub> = 60V, V <sub>GS</sub> = 0V
	—	—	250	—	V <sub>DS</sub> = 48V, V <sub>GS</sub> = 0V, T <sub>J</sub> = 150°C
I <sub>GSS</sub>	—	—	100	—	V <sub>GS</sub> = 20V
	—	—	-100	—	V <sub>GS</sub> = -20V
Q <sub>g</sub>	—	—	46	—	I <sub>D</sub> = 30A
Q <sub>gs</sub>	—	—	11	nC	V <sub>DS</sub> = 48V
Q <sub>gd</sub>	—	—	22	—	V <sub>GS</sub> = 10V, See Fig. 6 and 13 ④
t <sub>d(on)</sub>	—	13	—	—	V <sub>DD</sub> = 30V
t <sub>r</sub>	—	100	—	—	I <sub>D</sub> = 30A
t <sub>d(off)</sub>	—	29	—	—	R <sub>G</sub> = 12Ω
t <sub>f</sub>	—	52	—	—	R <sub>D</sub> = 1.0Ω, See Fig. 10 ④
L <sub>D</sub>	—	4.5	—	nH	Between lead, 6 mm (0.25 in.) from package and center of die contact
L <sub>C</sub>	—	7.5	—		
C <sub>iss</sub>	—	1300	—	—	V <sub>GS</sub> = 0V
C <sub>oss</sub>	—	640	—	pF	V <sub>DS</sub> = 25V
C <sub>rss</sub>	—	96	—	—	f = 1.0MHz, See Fig. 5
r	1340	—	1480	—	I <sub>D</sub> = 30A, V <sub>GS</sub> = 10V
C <sub>oss</sub>	—	9.0	—	pF	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 25V, f = 1.0MHz

## Source-Drain Ratings and Characteristics

Parameter	Min.	Typ.	Max.	Units	Conditions
I <sub>S</sub>	—	—	30	A	MOSFET symbol showing the integral reverse p-n junction diode. 
I <sub>SM</sub>	—	—	120		
V <sub>SD</sub>	—	—	1.6	V	T <sub>J</sub> = 25°C, I <sub>S</sub> = 30A, V <sub>GS</sub> = 0V ④
t <sub>rr</sub>	—	120	230	ns	T <sub>J</sub> = 25°C, I <sub>F</sub> = 30A
Q <sub>rr</sub>	—	0.70	1.4	nC	di/dt = 100A/μs ④
t <sub>on</sub>	Intrinsic turn-on time is negligible (turn-on is dominated by L <sub>S</sub> +L <sub>D</sub> )				

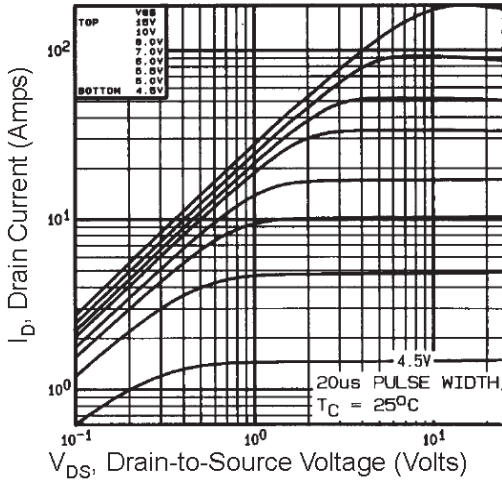
### Notes:

① Repetitive rating; pulse width limited by max. junction temperature. ( See fig. 11 )

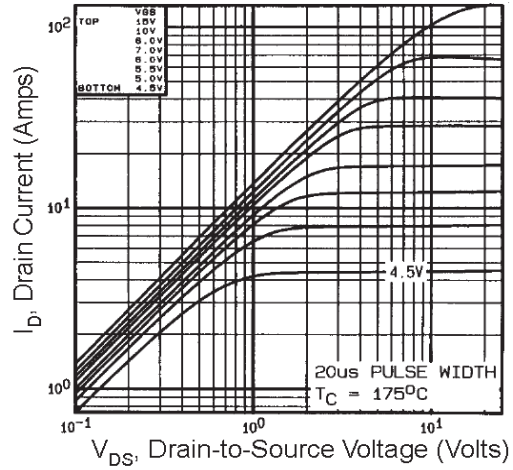
③ I<sub>SD</sub> ≤ 30A, di/dt ≤ 200A/μs, V<sub>DD</sub> ≤ V<sub>(BR)DSS</sub>, T<sub>J</sub> ≤ 175°C

② V<sub>DD</sub> = 25V, starting T<sub>J</sub> = 25°C, L = 0.019mH  
R<sub>G</sub> = 25Ω, I<sub>AS</sub> = 30A. (See Figure 12)

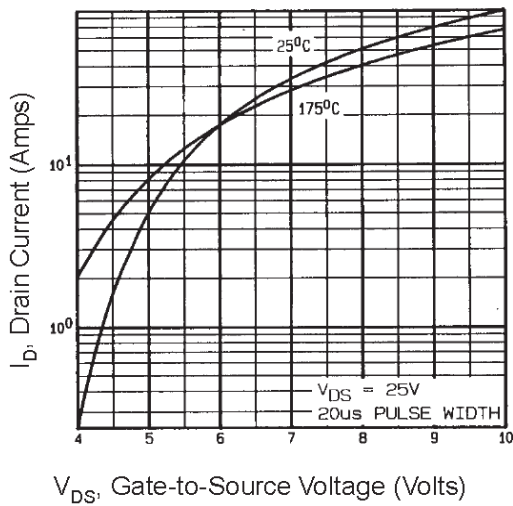
④ Pulse width ≤ 300μs; duty cycle ≤ 2%.



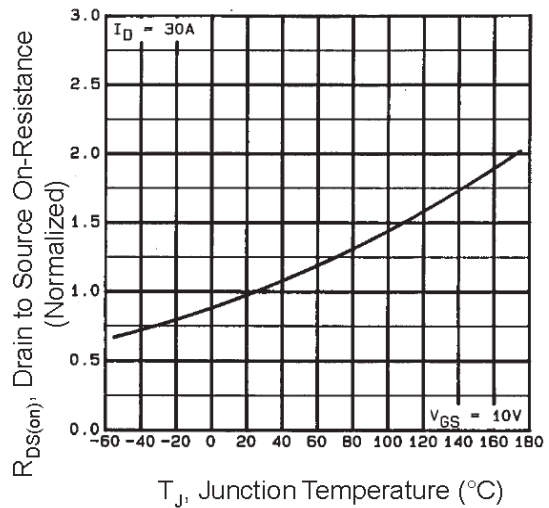
**Fig. 1 Typical Output Characteristics,**  
 $T_c=25^\circ\text{C}$



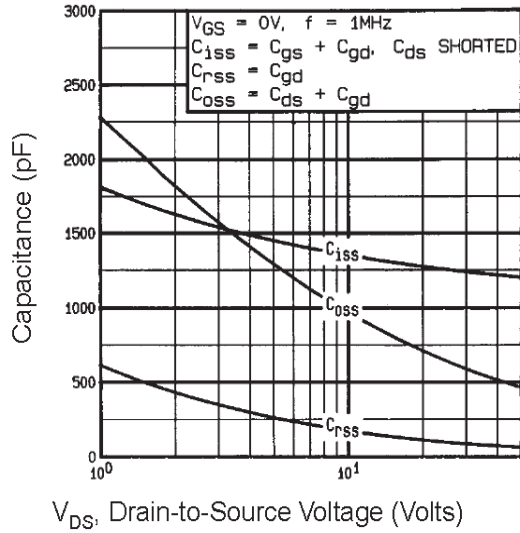
**Fig. 2 Typical Output Characteristics,**  
 $T_c=175^\circ\text{C}$



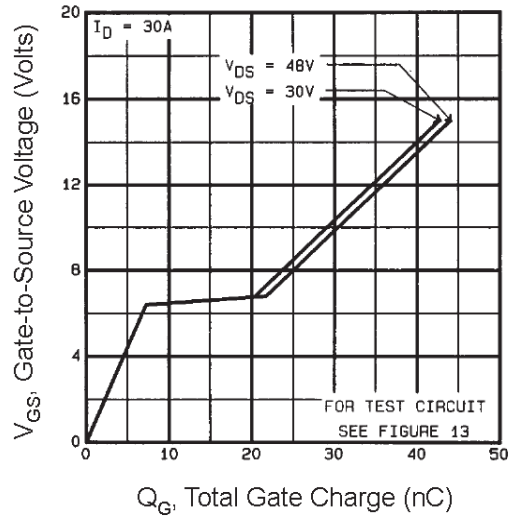
**Fig. 3 Typical Transfer Characteristics**



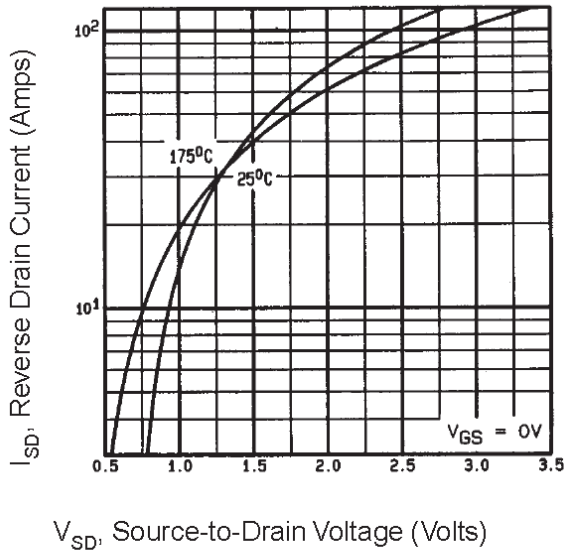
**Fig. 4 Normalized On-Resistance vs. Temperature**



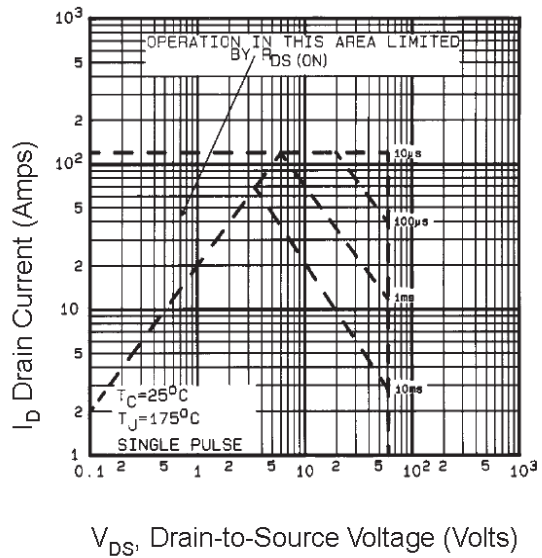
**Fig. 5 Typical Capacitance vs. Drain-to-Source Voltage**



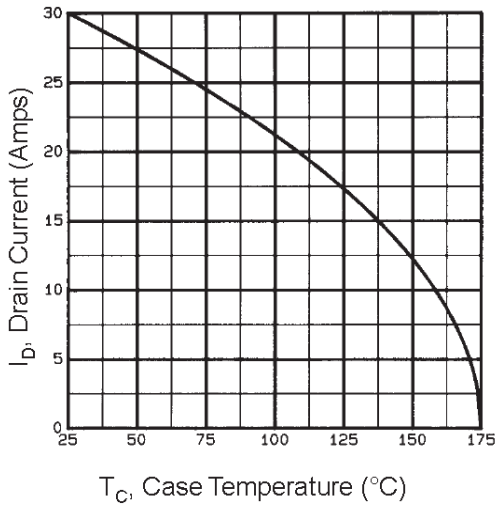
**Fig. 6 Typical Gate Charge vs. Gate-to-Source Voltage**



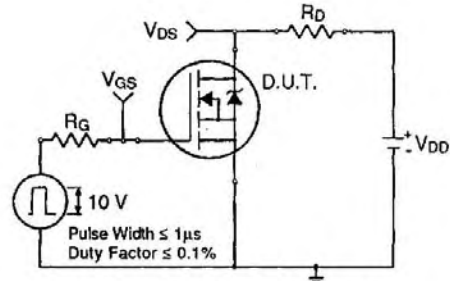
**Fig. 7 Typical Source-Drain Diode Forward Voltage**



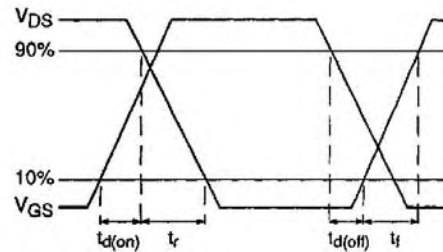
**Fig. 8 Maximum Safe Operating Area**



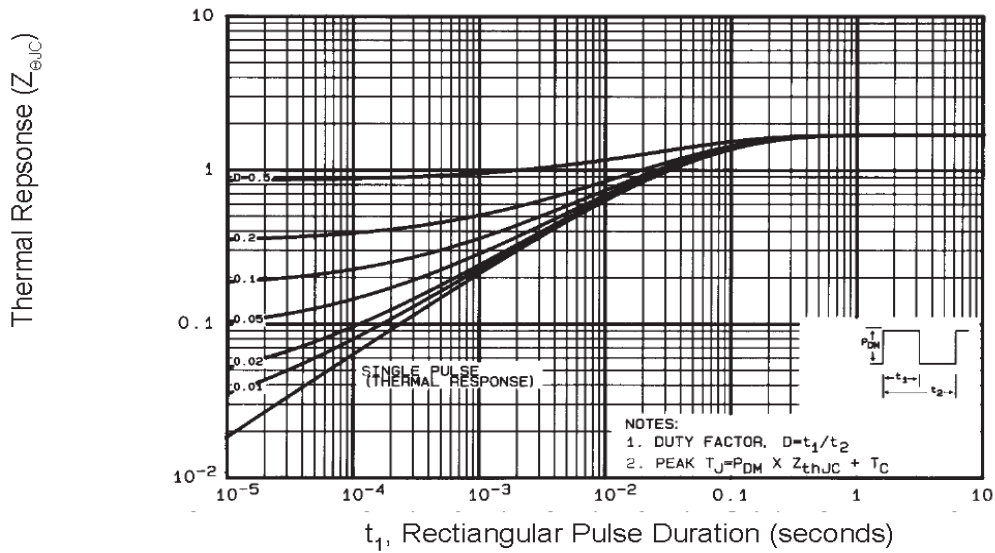
**Fig. 9 Maximum Drain Current vs. Case Temperature**



**Fig 10a. Switching Time Test Circuit**



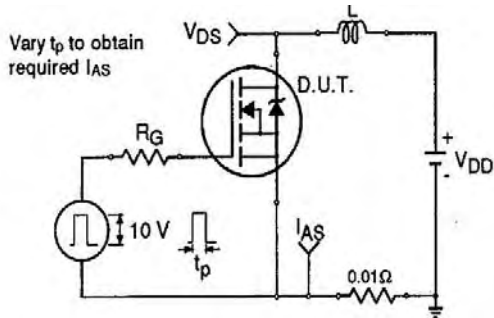
**Fig 10b. Switching Time Waveforms**



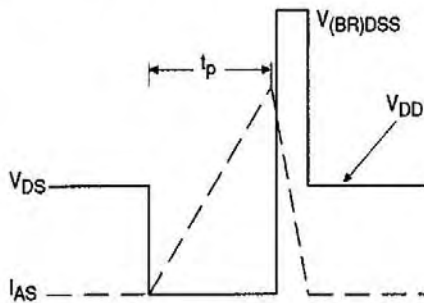
**Fig. 11 Maximum Effective Transient Thermal Impedance, Junction-to-Case**

# IRCZ34PbF

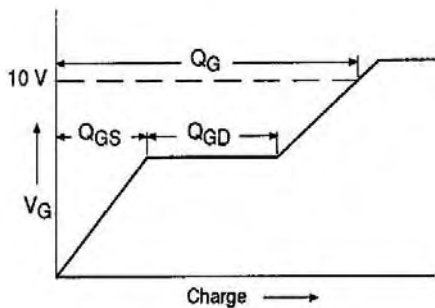
International  
**IR** Rectifier



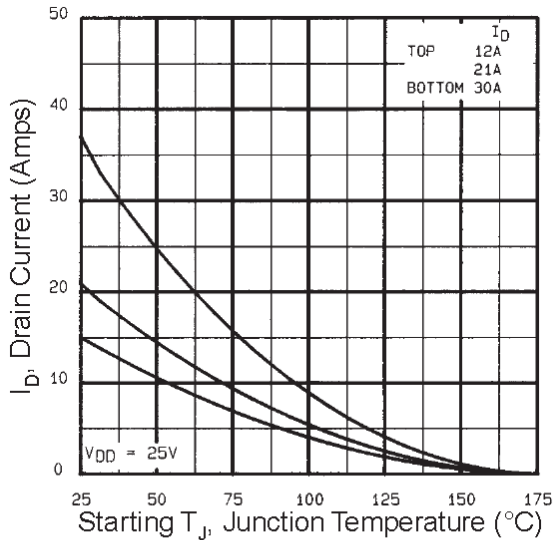
**Fig 12a.** Unclamped Inductive Test Circuit



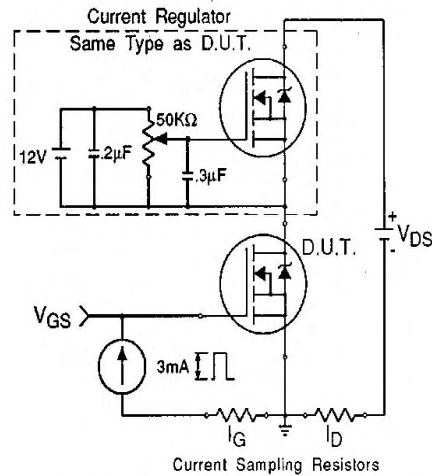
**Fig 12b.** Unclamped Inductive Waveforms



**Fig 13a.** Basic Gate Charge Waveform



**Fig. 12c Maximum Avalanche Energy vs. Drain Current**



**Fig 13b.** Gate Charge Test Circuit

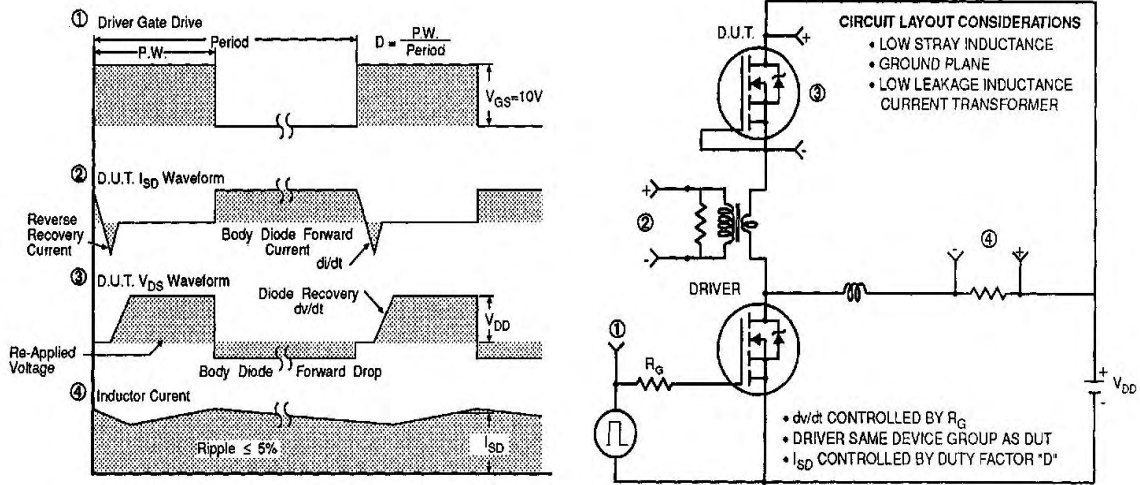


Fig 14. Peak Diode Recovery dv/dt Test Circuit

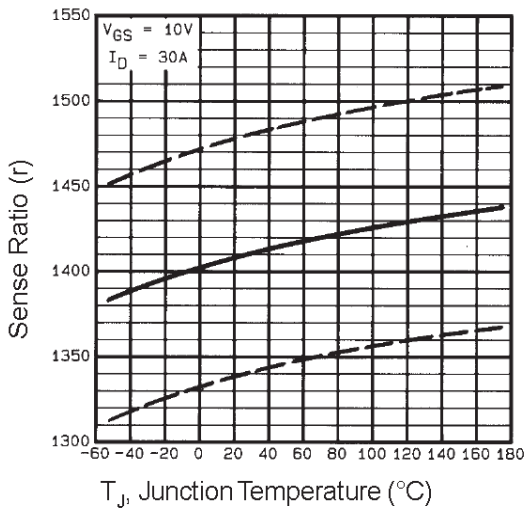


Fig. 15 Typical HEXSense Ratio vs. Junction Temperature

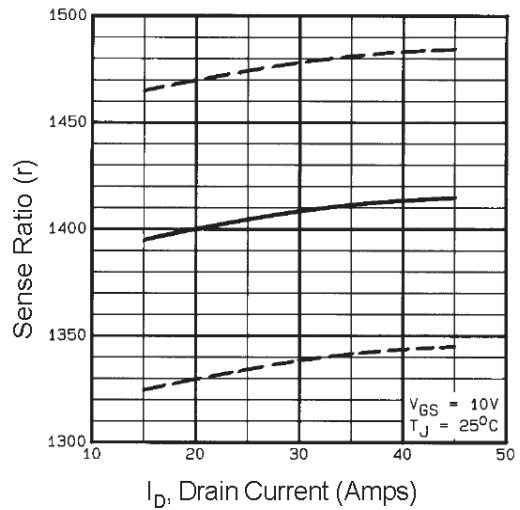
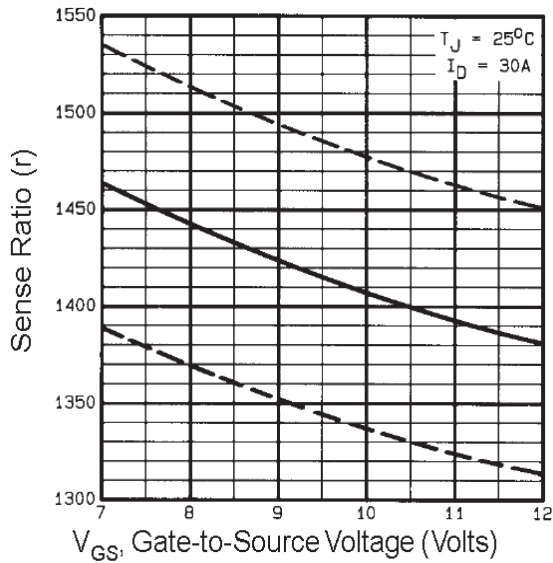
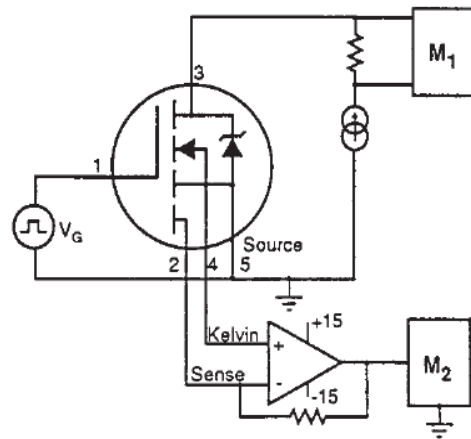


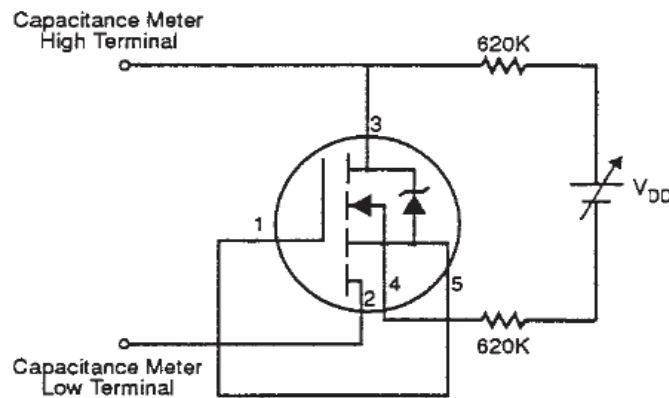
Fig. 16 Typical HEXSense Ratio vs. Drain Current



**Fig. 17 Typical HEXSense Ratio vs. Gate Voltage**



**Fig. 18 HEXSense Ratio Test Circuit**

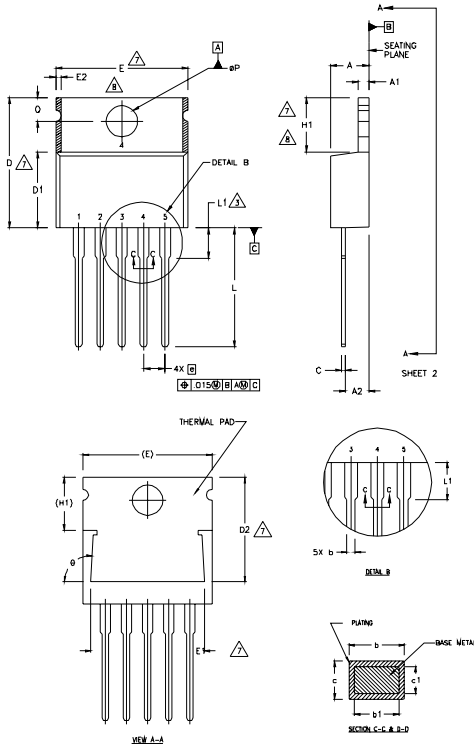


**Fig. 19 HEXSense Sensing Cell Output Capacitance Test Circuit**



## HexsenseTO-220 5L Package Outline

( Dimensions are shown in millimeters (inches) )



NOTES:

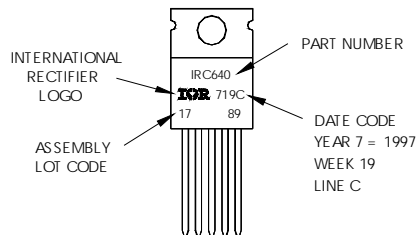
- 1 DIMENSIONING AND TOLERANCING PER ASME Y14.5 M- 1994.
- 2 DIMENSIONS ARE SHOWN IN INCHES [MILLIMETERS].
- 3 LEAD DIMENSION AND FINISH UNCONTROLLED IN L1.
- 4 DIMENSION D & E DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED .005" (0.127) PER SIDE. THESE DIMENSIONS ARE MEASURED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY.
- 5 DIMENSION b1 & c1 APPLY TO BASE METAL ONLY.
- 6 CONTROLLING DIMENSION : INCHES.
- 7 THERMAL PAD CONTOUR OPTIONAL WITHIN DIMENSIONS E,H1,D2 & E1
- 8 DIMENSION E2 X H1 DEFINE A ZONE WHERE STAMPING AND SINGULATION IRREGULARITIES ARE ALLOWED.

SYMBOL	DIMENSIONS				NOTES
	MILLIMETERS		INCHES		
	MIN.	MAX.	MIN.	MAX.	
A	3.56	4.82	.140	.190	
A1	0.51	1.40	.020	.055	
A2	2.04	2.92	.080	.115	
b	0.64	0.88	.025	.035	
b1	0.64	0.84	.025	.033	5
c	0.36	0.61	.014	.024	
c1	0.36	0.56	.014	.022	5
D	14.22	16.51	.560	.650	4
D1	8.38	9.02	.330	.355	
D2	12.19	12.88	.480	.507	7
E	9.66	10.66	.380	.420	4,7
E1	8.38	8.89	.330	.350	7
e	1.70 BSC		.067 BSC		
H1	5.85	6.55	.230	.270	7,8
L	13.47	14.09	.530	.555	
L1	-	6.35	-	.250	3
øP	3.54	4.08	.139	.161	
Q	2.54	3.42	.100	.135	
ø	90°-93°		90°-93°		

## Hexsense TO-220 5L Part Marking Information

EXAMPLE: THIS IS AN IRC640  
WITH ASSEMBLY  
LOT CODE 1789  
ASSEMBLED ON WW 19, 1997  
IN THE ASSEMBLY LINE "C"

Note: "P" in assembly line position  
indicates "Lead-Free"



Data and specifications subject to change without notice.